# **RB751V40T1G**

# **Schottky Barrier Diode**

These Schottky barrier diodes are designed for high speed switching applications, circuit protection, and voltage clamping. Extremely low forward voltage reduces conduction loss. Miniature surface mount package is excellent for hand held and portable applications where space is limited.

#### **Features**

- Extremely Fast Switching Speed
- Extremely Low Forward Voltage -0.28 Volts (Typ) @  $I_F = 1$  mAdc
- Low Reverse Current
- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Reverse Voltage	V <sub>RM</sub>	40	V
Reverse Voltage	V <sub>R</sub>	30	Vdc
Forward Continuous Current (DC)	I <sub>F</sub>	30 mA	
Peak Forward Surge Current	I <sub>FSM</sub>	500	mA
Electrostatic Discharge	E <sub>SD</sub>	HBM Class: 1C MM Class: A	

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR–5 Board, (Note 1) T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	200 1.57	mW mW/°C
Thermal Resistance Junction–to–Ambient	$R_{\theta JA}$	635	°C/W
Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. FR-5 Minimum Pad



# ON Semiconductor®

http://onsemi.com

# 40 V SCHOTTKY BARRIER DIODE





SOD-323 CASE 477 STYLE 1

# **MARKING DIAGRAM**



5E = Specific Device Code

M = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

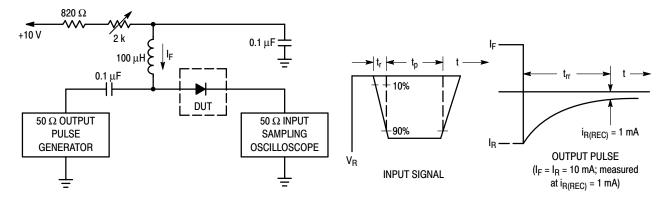
Device	Package	Shipping <sup>†</sup>
RB751V40T1G	SOD-323 (Pb-Free)	3000 / Tape & Reel
NSVRB751V40T1G	SOD-323 (Pb-Free)	3000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

# RB751V40T1G

# **ELECTRICAL CHARACTERISTICS** (T<sub>A</sub> = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage $(I_R = 10 \mu A)$	V <sub>(BR)R</sub>	30	-	-	Volts
Total Capacitance (V <sub>R</sub> = 1.0 V, f = 1.0 MHz)	СТ	-	2.0	2.5	pF
Reverse Leakage (V <sub>R</sub> = 30 V)	I <sub>R</sub>	-	300	500	nAdc
Forward Voltage (I <sub>F</sub> = 1.0 mAdc)	V <sub>F</sub>	-	0.28	0.37	Vdc

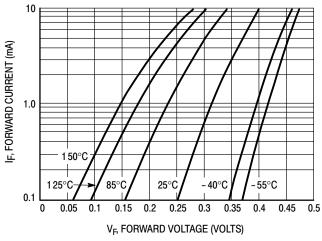


Notes: 1. A 2.0 k $\Omega$  variable resistor adjusted for a Forward Current (I<sub>F</sub>) of 10 mA.

- 2. Input pulse is adjusted so  $I_{R(peak)}$  is equal to 10 mA.
- $3.\ t_p \ \text{"}\ t_{rr}$

Figure 1. Recovery Time Equivalent Test Circuit

# **RB751V40T1G**



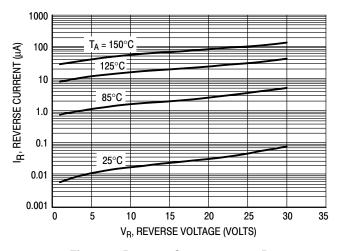


Figure 2. Typical Forward Voltage

Figure 3. Reverse Current versus Reverse Voltage

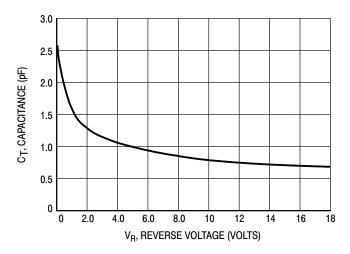


Figure 4. Typical Capacitance

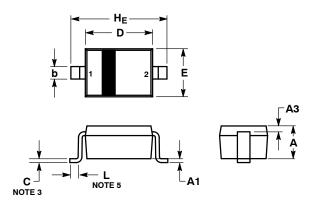




SOD-323 CASE 477-02 **ISSUE H** 

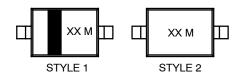
**DATE 13 MAR 2007** 

#### SCALE 4:1





### **GENERIC MARKING DIAGRAM\***



XX = Specific Device Code M = Date Code

#### NOTES

- NOTES:

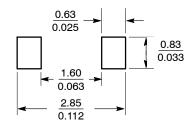
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETERS.

  3. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.
- 4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
  5. DIMENSION L IS MEASURED FROM END OF RADIUS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.80	0.90	1.00	0.031	0.035	0.040
A1	0.00	0.05	0.10	0.000	0.002	0.004
А3	0.15 REF		0.006 REF			
b	0.25	0.32	0.4	0.010	0.012	0.016
С	0.089	0.12	0.177	0.003	0.005	0.007
D	1.60	1.70	1.80	0.062	0.066	0.070
E	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
HE	2.30	2.50	2.70	0.090	0.098	0.105

## RECOMMENDED **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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DESCRIPTION:	SOD-323		PAGE 1 OF 1	

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